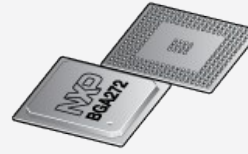# MPC555LFMZP40

(Not Recommended for New Designs)

MPC500 32-bit MCU, PowerPC core, 448KB Flash, 40MHz, PBGA 272

📄 Data Sheet   🔲 Product Summary

🔧 Software & Tools   📄 Documentation

Package :
📦 BGA272

BGA272, plastic, ball grid array; 272 balls; 1.27 mm pitch; 27 mm x 27 mm x 1.95 mm body

Buy Options | Operating Characteristics | Environmental Information | Quality Information | Shipping Information | Replacement Data

Operating Characteristics

Parameter	Value
Maturity	Product

Parameter	Value
Description	MPC500 32-bit MCU, PowerPC core, 448KB Flash, 40MHz, PBGA 272

Environmental Information

Material Declaration	PbFree	EU RoHS	Halogen Free	RHF Indicator	2nd Level Interconnect	REACH SVHC	Weight (mg)
⌀ MPC555LFMZP40 (935316699557) Replacement: MPC555LFMVR40	No	No	No	N	e0	REACH SVHC	2615.1

Quality Information

Material Declaration	Safe Assure Functional Safety	Moisture Sensitivity Level (MSL)	Peak Package Body Temperature (PPT) (C°)	Maximum Time at Peak Temperatures (s)
		Lead Soldering	Lead Soldering	Lead Soldering
⌀ MPC555LFMZP40 (935316699557) Replacement: MPC555LFMVR40	No	3	235	30

Shipping Information

Part Number	Harmonized Tariff (US) Disclaimer	Export Control Classification Number (US)
⌀ MPC555LFMZP40 (935316699557) Replacement: MPC555LFMVR40	854231	3A991A2

Discontinued and Replacement Part Data

Part Number / 12NC	Discontinuance Notice	Replacement	Status	Comments
MPC555LFMZP40 (935316699557)	-	MPC555LFMVR40	Not Recommended for New Designs	Replacement Reason: Regulatory or Legal Change

ABOUT NXP

Investors

Press, News, Blogs

Careers

RESOURCES

Mobile Apps

Contact Us

FOLLOW US

News 26 Jul 2018

NXP Semiconductors Reports Second Quarter 2018 Results

Read More

Privacy | Terms of Use | Terms of Sale | Feedback